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(12) **United States Design Patent**
Lim et al.

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(45) **Date of Patent: ** Apr. 29, 2014**

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(54) **POWER SEMICONDUCTOR MODULE**

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(**) Term: **14 Years**

(21) Appl. No.: **29/450,498**

(22) Filed: **Mar. 18, 2013**

(30) **Foreign Application Priority Data**

Dec. 6, 2012 (KR) 30-2012-0058592

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/110, 182; 361/713, 714, 715, 728, 361/736, 752, 774, 775, 783, 784, 785, 361/813; 257/668, 678, 684, 690
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

5,408,128	A	*	4/1995	Furnival	257/690
D364,383	S		11/1995	Yamada et al.	
D364,384	S	*	11/1995	Shimizu et al.	D13/182
D364,385	S	*	11/1995	Shimizu et al.	D13/182
6,078,501	A	*	6/2000	Catrambone et al.	361/704
D441,726	S	*	5/2001	Sofue et al.	D13/182
D448,739	S	*	10/2001	Iwasaki et al.	D13/182
D476,959	S	*	7/2003	Yamada et al.	D13/182
7,425,757	B2	*	9/2008	Takubo	257/678
D587,662	S	*	3/2009	Soutome et al.	D13/182
D589,012	S	*	3/2009	Soyano et al.	D13/182
D606,951	S	*	12/2009	Soyano et al.	D13/182
D648,290	S	*	11/2011	Mori	D13/182
D653,633	S	*	2/2012	Soyano	D13/182
D653,634	S	*	2/2012	Soyano	D13/182
D674,760	S	*	1/2013	Mochizuki et al.	D13/182
D686,174	S	*	7/2013	Soyano	D13/182
2001/0038143	A1	*	11/2001	Sonobe et al.	257/690
2010/0149774	A1	*	6/2010	Matsumoto et al.	361/783
2011/0044012	A1	*	2/2011	Matsumoto	361/728

* cited by examiner

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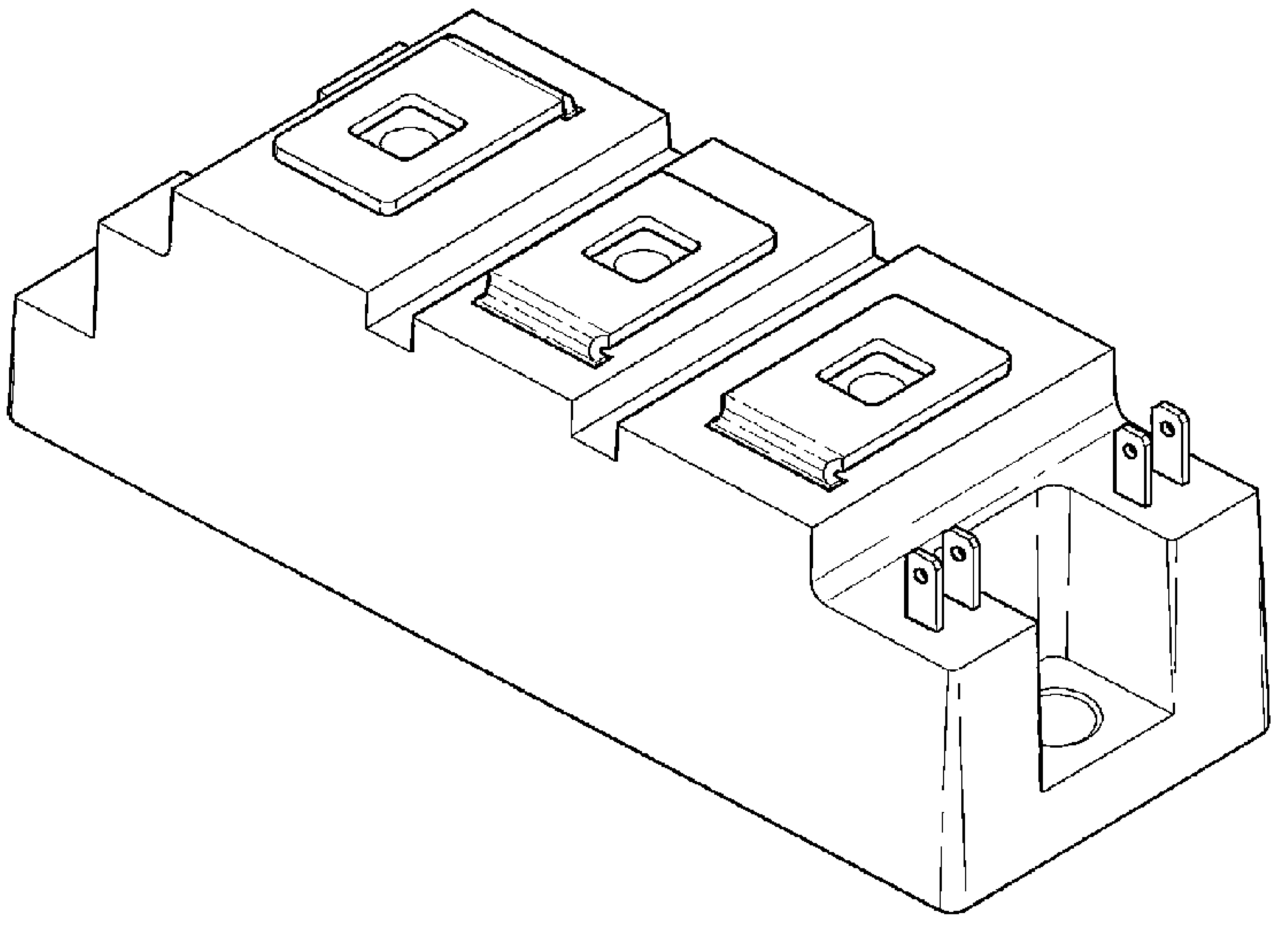
(57) **CLAIM**

The ornamental design for a power semiconductor module, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a power semiconductor module showing our new design;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a left-side view thereof;
FIG. **5** is a right-side view thereof;
FIG. **6** is a top plan view thereof; and,
FIG. **7** is a bottom plan view thereof.

1 Claim, 4 Drawing Sheets



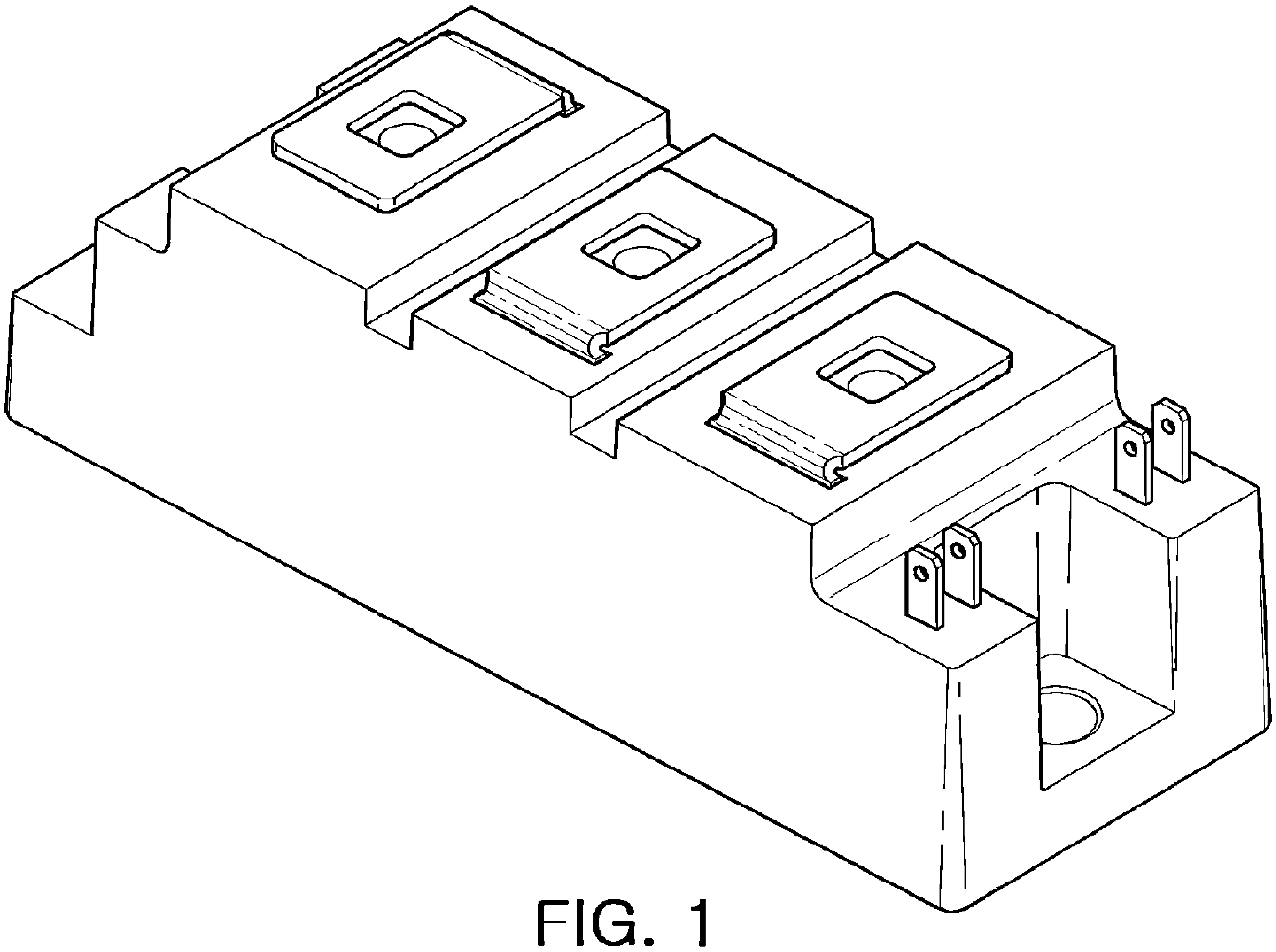


FIG. 1

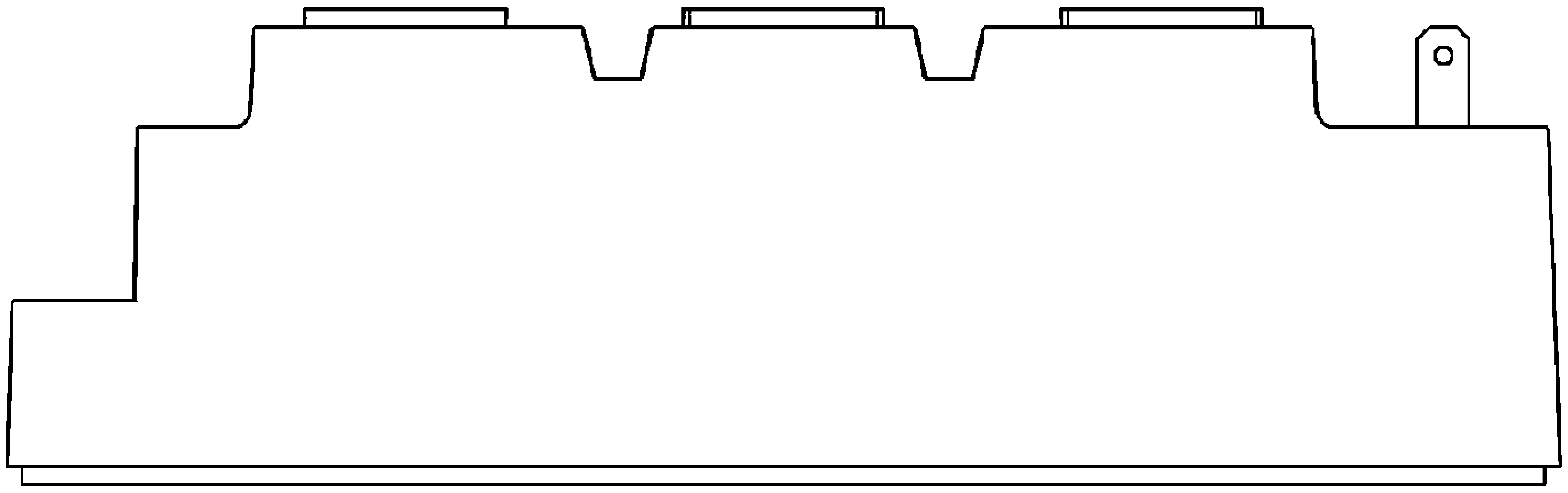


FIG. 2

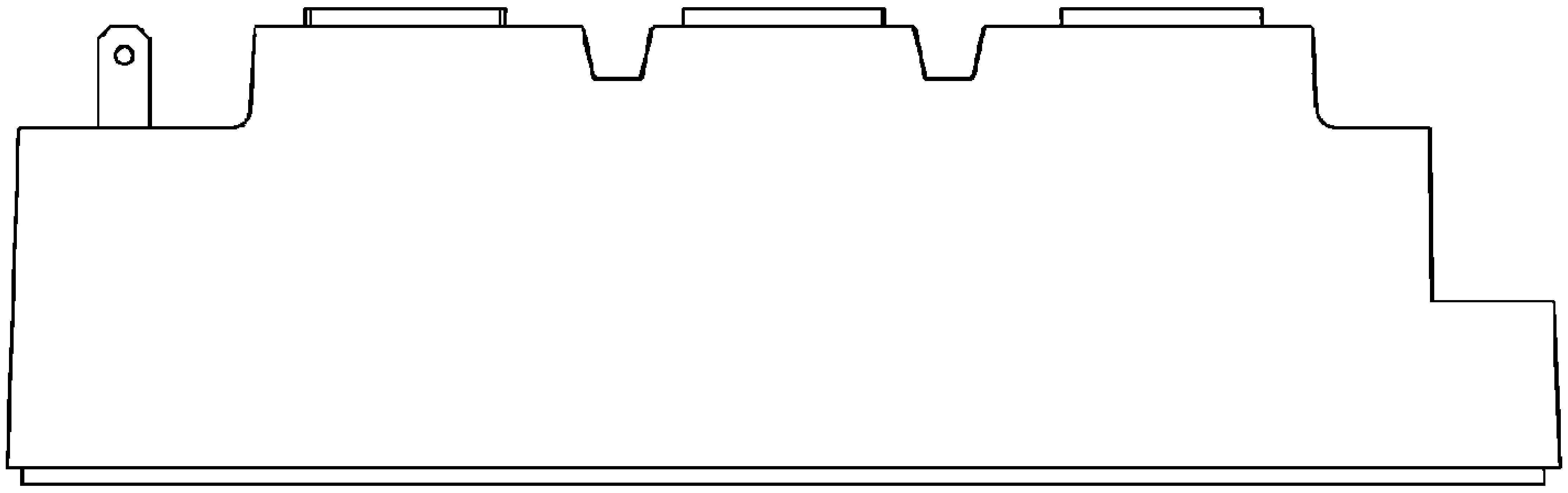


FIG. 3

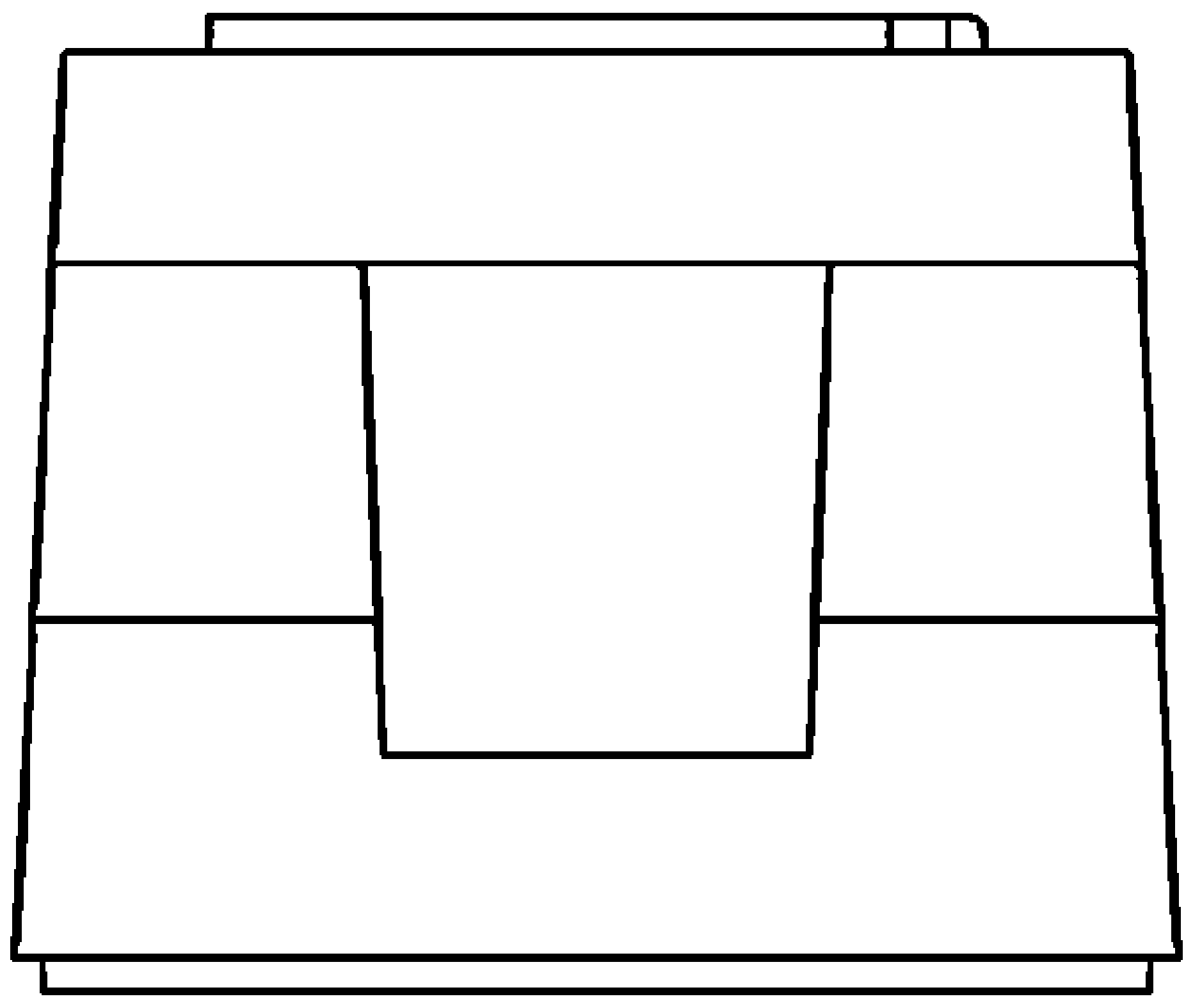


FIG. 4

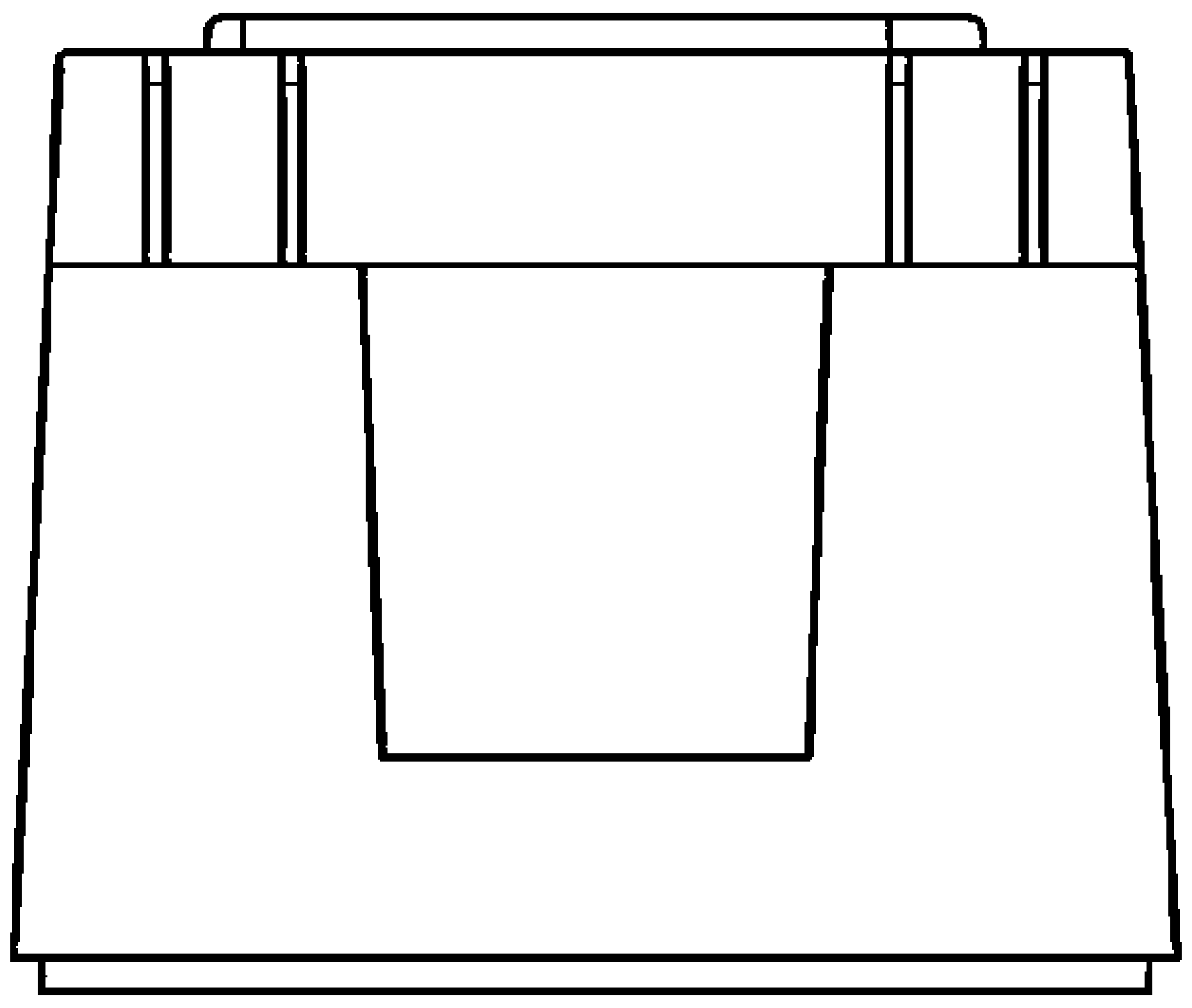


FIG. 5

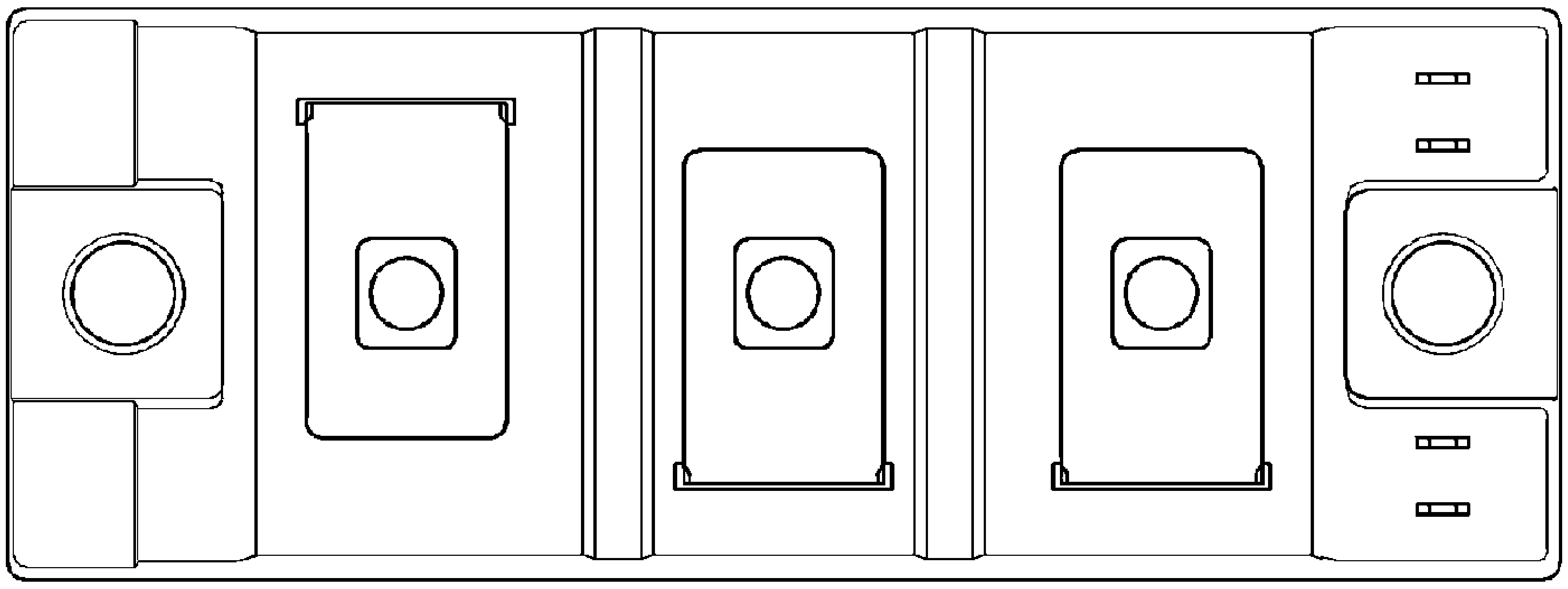


FIG. 6

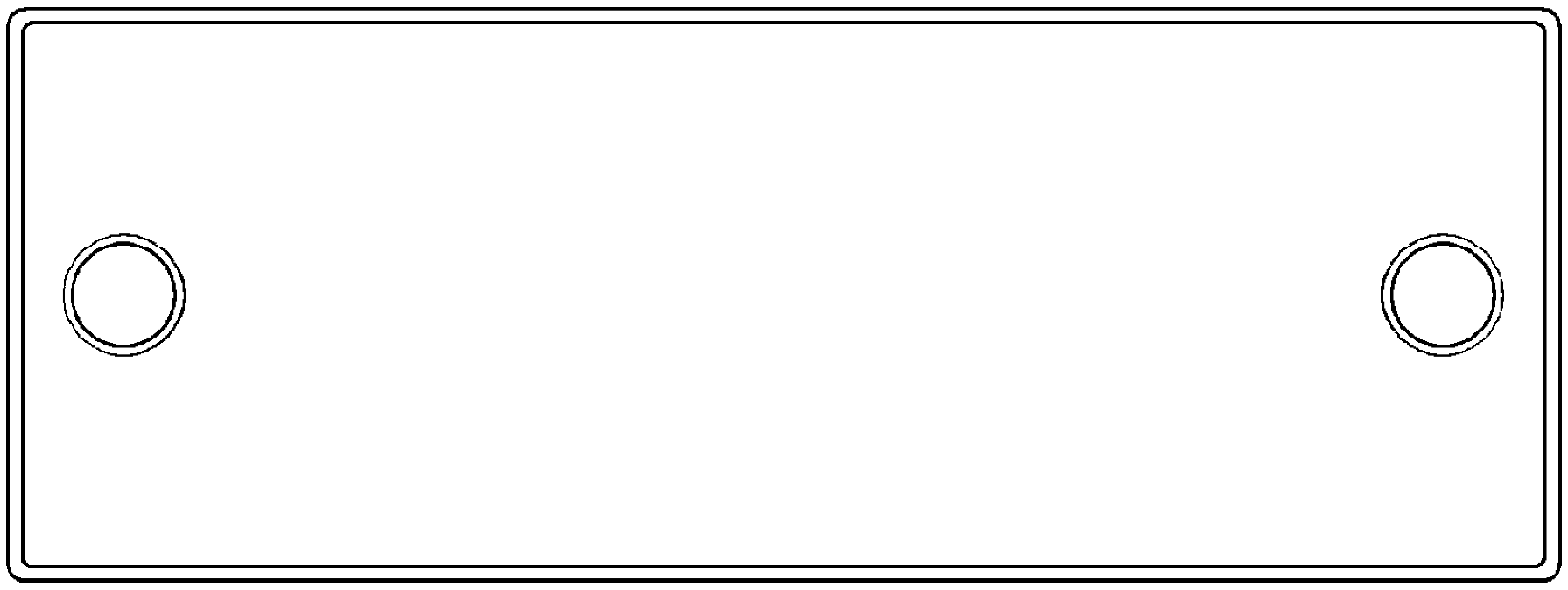


FIG. 7

UNITED STATES PATENT AND TRADEMARK OFFICE

CERTIFICATE OF CORRECTION

PATENT NO. : D703,625 S
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INVENTOR(S) : Jae Hyun Lim et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the title page, item (72) Inventors should read: Jae Hyun LIM, Gyunggi-do (KR); Young Ki Lee, Gyunggi-do (KR); Tae Hyun Kim, Gyunggi-do (KR); Si Joong Yang, Gyunggi-do (KR); Jong Man Kim, Gyunggi-do (KR); Kyu ~~Kwan~~ <u>Hwan</u> Oh, Gyunggi-do (KR); Young Ho Sohn, Gyunggi-do (KR).

Signed and Sealed this
Second Day of September, 2014

Michelle K. Lee

Michelle K. Lee
Deputy Director of the United States Patent and Trademark Office